

Customer No.: 31561  
Docket No.: 13689-US-PA  
Application No.: 10/711,674

**In The Claims:**

Claim 1. (currently amended) A bonding pad for disposing on a chip, comprising:

a body having a first surface and a corresponding second surface and having a central region and corner regions, wherein the body is disposed on the chip, and the second surface of the body is in contact with the chip; and

at least one first protruding portion disposed on the first surface at the corner regions of the body.

Claim 2. (original) The bonding pad of claim 1, further comprising a second protruding portion disposed on the first surface in the central region of the body.

Claim 3. (original) The bonding pad of claim 2, wherein the second protruding portion is connected to the first protruding portion.

Claim 4. (original) The bonding pad of claim 2, wherein the shape of the second protruding portion when viewed from the top against the first surface is selected from the group consisting of a cross-line shape, a circular shape, a circular ring shape, an ellipse shape, an ellipse ring shape, a polygonal shape, a polygonal ring shape, a linear shape, a geometrical shape and combinations thereof.

Claim 5. (original) The bonding pad of claim 3, wherein the shape of the second protruding portion when viewed from the top against the first surface is selected from the group consisting of a cross-line shape, a circular shape, a circular ring shape, an ellipse shape, an ellipse

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ring shape, a polygonal shape, a polygonal ring shape, a linear shape, a geometrical shape and combinations thereof.

Claim 6. (currently amended) The bonding pad of claim 2, wherein the materials for the body, the first protruding portion and the second protruding portion are identical formed together as single unit.

Claim 7. (currently amended) The bonding pad of claim 1, wherein the materials for the body and the first protruding portion are identical formed together as a single unit.

Claim 8. (original) The bonding pad of claim 1, wherein the material constituting the bonding pad comprises aluminum.

Claim 9. (original) The bonding pad of claim 1, wherein the body has a four-sided geometric shape.

Claim 10. (currently amended) A chip structure, comprising:

a chip having an active surface;

at least one bonding pad disposed on the active surface of the chip, the bonding pad including:

a body having a first surface and a corresponding second surface and having a central region and corner regions, wherein the body is disposed on the chip, and the second surface of the body is in contact with the chip; and

at least one first protruding portion disposed on the first surface at the corner regions of the body.

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Claim 11. (original) The chip structure of claim 10, wherein the bonding pad further comprises a second protruding portion disposed on the first surface in the central region of the body.

Claim 12. (original) The chip structure of claim 11, wherein the second protruding portion is connected to the first protruding portion.

Claim 13. (original) The chip structure of claim 11, wherein the shape of the second protruding portion when viewed from the top against the first surface is selected from the group consisting of a cross-line shape, a circular shape, a circular ring shape, an ellipse shape, an ellipse ring shape, a polygonal shape, a polygonal ring shape, a linear shape, a geometrical shape and combinations thereof.

Claim 14. (original) The chip structure of claim 12, wherein the shape of the second protruding portion when viewed from the top against the first surface is selected from the group consisting of a cross-line shape, a circular shape, a circular ring shape, an ellipse shape, an ellipse ring shape, a polygonal shape, a polygonal ring shape, a linear shape, a geometrical shape and combinations thereof.

Claim 15. (currently amended) The chip structure of claims 11, wherein the materials for the body, the first protruding portion and the second protruding portion are identical ~~the bonding pad is a single unit.~~

Claim 16. (currently amended) The chip structure of claims 10, wherein the materials for the body and the first protruding portion are identical ~~the bonding pad is a single unit.~~

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Claim 17. (original) The chip structure of claim 10, wherein the material constituting the bonding pad comprises aluminum.

Claim 18. (original) The chip structure of claim 10, wherein the body has a four-sided geometric shape.

Claim 19. (original) The chip structure of claim 10, further comprising a passivation layer disposed on the active surface of the chip that also covers the peripheral region of the bonding pad but leaves the central region of the bonding pad exposed.

Claim 20. (original) The chip structure of claim 10, further comprising at least a bump disposed on and electrically connected with the bonding pad.

Claim 21. (currently amended) A pad for disposing on a chip, comprising:

a body having a central region and corner regions; and

at least one first protruding portion disposed on corner regions of the body.

Claim 22. The pad of claim 21, further comprising a second protruding portion disposed on central region of the body.

Claim 23. (original) A display apparatus comprising a device which includes the pad of claim 21.

Claim 24. (original) The display apparatus of claim 23, wherein the pad further comprises a second protruding portion disposed on central region of the body.

Claim 25. (original) The display apparatus of claim 24, wherein the second protruding portion is connected to the first protruding portion.

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Claim 26. (original) A device comprising the pad of claim 21.

Claim 27. (original) The device of claim 26, wherein the pad further comprises a second protruding portion disposed on central region of the body.

Claim 28. (original) The device of claim 27, wherein the second protruding portion is connected to the first protruding portion.